REVISION RECORD		
REV	DESCRIPTION	DATE
0	INITIAL RELEASE	06/03/99
A	PAGE 9, FIGURE 4, CHANGED θJA AND θJC.	09/28/99
B	PAGE 3, PARAGRAPH 3. 8 CHANGED VERBIAGE ADDED "HEREIN " AFTER TABLE 1. PAGE 4, PARAGRAPH 5. 0 CHANGED VERBIAGE ADDED "HEREIN" AFTER TABLE 3. PARAGRAPH 5.2 ADDED "HEREIN" AFTER TABLE 2. PARAGRAPH 6.2, CHANGED VERBIAGE ADDED "HEREIN" AFTER TABLE 3. PAGE 5, PARAGRAPH 6.3, CHANGED VERBIAGE ADDED "HEREIN" AFTER TABLE 3.	12/06/99
C	THROUGHOUT SPECIFICATION CHANGED PART NUMBER FROM (RH1085M) TO (RH1085MK) REQUIREMENT.	02/15/01
D	•PAGE 1, CORRECTED THE CAGE CODE NUMBER FROM "94155" TO "64155". •PAGE 2, PARAGRAPH 3.2, ADDED DIE REVISIONS "A" AND "B" AVAILABILITY. •PAGE 3, PARAGRAPH 3.6, CHANGED DIE OUTLINES AND PAD FUNCTIONS TO "FIGURE 1A" FOR DIE REVISION A AND "FIGURE 1B" FOR DIE REVISION B. PARAGRAPH 3.7.1, CHANGED THE DOSAGE RATE FROM "APPROXIMATELY 20 RADS PER SECOND" TO "LESS THAN OR EQUAL TO 10 RADS PER SECOND". • PAGE 4, PARAGRAPH 6.1 CHANGED QUALITY ASSURANCE PROVISIONS TO STATE THAT LTC IS QML CERTIFIED AND THAT RAD HARD CANDIDATES ARE ASSEMBLED ON QUALIFIED ON CLASS S MANUFACTURING LINES. •PAGE 6, IS DICE OUTLINE DIMENSIONS AND PAD FUNCTIONS, FIGURE 1A. •PAGE 7, IS DICE OUTLINE DIMENSIONS AND PAD FUNCTIONS, FIGURE 1B. •PAGE 9, BURN-IN CIRCUIT CHANGED FROM "Tj = 170°C AT Ta OF 150°C" TO "Tj = 168°C MAX AT Ta OF 150°C".	03/08/05
E	• PAGE 3, PARAGRAPH 3.7.1 CHANGED VERBIAGE. • PAGE 4, PARAGRAPH 5.8 CHANGED ALLOY 42 TO ALLOY 52 REQUIRED ON TO3 PACKAGE.	05/13/08
F	• PAGE 9, FIGURE 3 STATIC BURN IN CIRCUIT CHANGED TO 04-06-0302 PER. ENG. PAGE 14, CHANGED RH CANNED SAMPLE TABLE III FOR QUALIFYING DICE SALES ADDED TEMPERATURE CYCLE, CONSTANT ACCELERATION & REMOVED PIND TEST.	03/03/09
G	PAGE 13, UPDATED REFERENCE VOLTAGE vs. POST-IRRADIATION LIMITS IN TABLE II ELECTRICAL CHARACTERISTICS. NOTE ADDED RELATED TO TABLE II. NOTES RENUMBERED ON TABLE II. NEW NOTE IS NOW NOTE 1.	12/06/10

CAUTION: ELECTROSTATIC DISCHARGE SENSITIVE PART

REVISION	PAGE NO.	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	
INDEX	REVISION	**J**	**J**	**J**	**J**	**J**	**J**	**J**	**J**	**J**	**J**	**J**	**J**	**J**	**J**	**J**	
REVISION	PAGE NO.																
INDEX	REVISION																

				ANALOG DEVICES INC,
	ORIG			
	DSGN			TITLE:
	ENGR			**MICROCIRCUIT, LINEAR, RH1085MK, 3.0A LOW DROPOUT POSITIVE REGULATOR DICE**
	MFG			
	CM			
	QA			SIZE:
	PROG			**64155** / **05-08-5140** / **K**
APPLICATION	FUNCT	SIGNOFFS	DATE	CONTRACT:

SIZE | CAGE CODE | DRAWING NUMBER | REV

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REVISION RECORD		
REV	DESCRIPTION	DATE
H	Page 3, amended section 3.3 Special Handling of Dice to more accurately describe our current procedures and requirements.	04/05/12
I	Page 15, Changed RH Canned Sample Table for Qualifying Dice Sales: Subgroup 6 Sample Size Series changed from 45 (3) to 65 (3). First note had the Sample Size Series from “15%” to “10%”.	07/02/13
J	Updated Die Sales table on pg 15.	6/1/15
K	**remove source and change Linear to Analog**	**2/2//21**

1.0 SCOPE:

1.1 This specification defines the performance and test requirements for a microcircuit processed to a space level manufacturing flow.

2.0 APPLICABLE DOCUMENTS:

2.1 Government Specifications and Standards: the following documents listed in the Department of Defense Index of Specifications and Standards, of the issue in effect on the date of solicitation, form a part of this specification to the extent specified herein.

SPECIFICATIONS:

MIL-PRF-38535	Integrated Circuits (Microcircuits) Manufacturing, General Specification for
MIL-STD-883	Test Method and Procedures for Microcircuits
MIL-STD-1835	Microcircuits Case Outlines

2.2 Order of Precedence: In the event of a conflict between the documents referenced herein and the contents of this specification, the order of precedence shall be this specification, MIL-PRF-38535 and other referenced specifications.

3.0 REQUIREMENTS:

3.1 General Description: This specification details the requirements for the RH1085MK, 3.0A, LOW DROPOUT POSITIVE REGULATOR DICE and Element Evaluation Test Samples, processed to space level manufacturing flow as specified herein.

3.2 Part Number: **RH1085MK, Dice, Revision A and/or Revision B.**

3.3 **Special Handling of Dice:** Rad Hard dice require special handling as compared to standard IC dice. Rad Hard dice are susceptible to surface damage due to the absence of silicon nitride passivation that is present on most standard dice. Silicon nitride protects the dice surface from scratches by its hard and dense properties. The passivation on Analog Devices Rad Hard dice is silicon dioxide which is much "softer" than silicon nitride. During the visual and preparation for shipment, ESD safe Tweezers are used and only the edge of the die are touched.

ADI recommends that dice handling be performed with extreme care so as to protect the die surface from scratches. If the need arises to move the die in or out of the chip shipment tray (waffle pack), use an ESD-Safe-Plastic-tipped Bent Metal Vacuum Probe, preferably .020" OD x .010" ID (for use with tiny parts). The wand should be compatible with continuous air vacuums. The tip material should be static dissipative Delrin (or equivalent) plastic.

During die attach, care must be exercised to ensure no tweezers, or other equipment, touch the top of the dice.

3.4 The Absolute Maximum Ratings:

Power Dissipation	Internally Limited
Input to output Voltage Differential	30v
Operating Temperature Range	
Control Section	-55°C to 150°C
Power Transistor	-55°C to 200°C

Storage Temperature Range	-65°C to 150°C
Lead Temperature (soldering, 10 sec.)	300°C

3.5 Design, Construction, and Physical Dimensions: Detail design, construction, physical dimensions, and electrical requirements shall be specified herein.

3.6 Outline Dimensions and Pad Functions: Dice outline dimensions, pad functions, and locations shall be specified in **Figure 1A (Revision A) and Figure 1B (Revision B)**.

3.7 Radiation Hardness Assurance (RHA):

3.7.1 The manufacturer shall perform a lot sample test as an internal process monitor for total dose radiation tolerance. The sample test is performed with MIL-STD-883 TM1019 Condition A as a guideline.

3.7.2 For guaranteed radiation performance to MIL-STD-883, Method 1019, total dose irradiation, the manufacturer will provide certified RAD testing and report through an independent test laboratory when required as a customer purchase order line item.

3.7.3 Total dose bias circuit is specified in **Figure 2**.

3.8 Wafer (or Dice) Probe: Dice shall be 100% probed at Ta = +25°C to the limits shown in **Table I** herein. All reject dice shall be removed from the lot. This testing is normally performed prior to dicing the wafer into chips. Final specifications after assembly are sample tested during the element evaluation.

3.9 Wafer Lot Acceptance: Wafer lot acceptance shall be in accordance with MIL-PRF-38535, Appendix A, except for the following: Top side glassivation thickness shall be a **minimum of 4KÅ.**

3.10 Wafer Lot Acceptance Report: SEM is performed per MIL-STD-883, Method 2018. Copies of SEM photographs shall be supplied with the Wafer Lot Acceptance Report as part of a Space Data Pack when specified as a customer purchase order line item.

3.11 Traceability: Wafer Diffusion Lot and Wafer traceability shall be maintained through Quality Conformance Inspection.

4.0 QUALITY CONFORMANCE INSPECTION: Quality Conformance Inspection shall consist of the tests and inspections specified herein.

5.0 SAMPLE ELEMENT EVALUATION: A sample from **each wafer supplying dice** shall be assembled and subjected to element evaluation per **Table III** herein.

5.1 100 Percent Visual Inspection: All dice supplied to this specification shall be inspected in accordance with MIL-STD-883, Method 2010, Condition A. All reject dice shall be removed from the lot.

5.2 Electrical Performance Characteristics for Element Evaluation: The electrical performance characteristics shall be as specified in **Table I** and **Table II** herein.

5.3 Sample Testing: Each wafer supplying dice for delivery to this specification shall be subjected to element evaluation sample testing. No dice shall be delivered until all the lot sample testing has been performed and the results found to be acceptable unless the customer supplies a written approval for shipment prior to completion of wafer qualification as specified in this specification.

5.4 Part Marking of Element Evaluation Sample Includes**:**

5.4.1 LTC Logo

5.4.2 LTC Part Number

5.4.3 Date Code

5.4.4 Serial Number

5.4.5 ESD Identifier per MIL-PRF-38535, Appendix A

5.4.6 Diffusion Lot Number

5.4.7 Wafer Number

5.5 Burn-In Requirement: Burn-In circuit for TO3 package is specified in **Figure 3**.

5.6 Mechanical/Packaging Requirements: Case Outline and Dimensions are in accordance with **Figure 4.**

5.7 Terminal Connections: The terminal connections shall be as specified in **Figure 5.**

5.8 Lead Material and Finish: The lead material and finish shall be alloy 52 with hot solder dip (Finish letter A) in accordance with MIL-PRF-38535.

6.0 VERIFICATION (QUALITY ASSURANCE PROVISIONS)

6.1 Quality Assurance Provisions: Quality Assurance provisions shall be in accordance with MIL-PRF-38535. Analog Devices is a QML certified company and all Rad Hard candidates are assembled on qualified Class S manufacturing lines.

6.2 Sampling and Inspection: Sampling and Inspection shall be in accordance with **Table III** herein.

6.3 Screening: Screening requirements shall be in accordance with **Table III** herein.

6.3.1

6.4 Deliverable Data: Deliverable data that will ship with devices when a Space Data Pack is ordered:

6.4.1 Lot Serial Number Sheets identifying all Canned Sample devices accepted through final inspection by serial number.

6.4.2 100% attributes (completed element evaluation traveler).

6.4.3 Element Evaluation variables data, including Burn-In and Op Life

6.4.4 SEM photographs (3.10 herein)

6.4.5 Wafer Lot Acceptance Report (3.9 herein)

6.4.6 A copy of outside test laboratory radiation report if ordered

6.4.7 Certificate of Conformance certifying that the devices meet all the requirements of this specification and have successfully completed the mandatory tests and inspections herein.

Note: Items 6.4.1 and 6.4.7 will be delivered as a minimum, with each shipment.

7.0 Packaging Requirements: Packaging shall be in accordance with Appendix A of MIL-PRF-38535. All dice shall be packaged in multicavity containers composed of conductive, anti-static, or static dissipative material with an external conductive field shielding barrier

DICE OUTLINE DIMENSIONS AND PAD FUNCTIONS

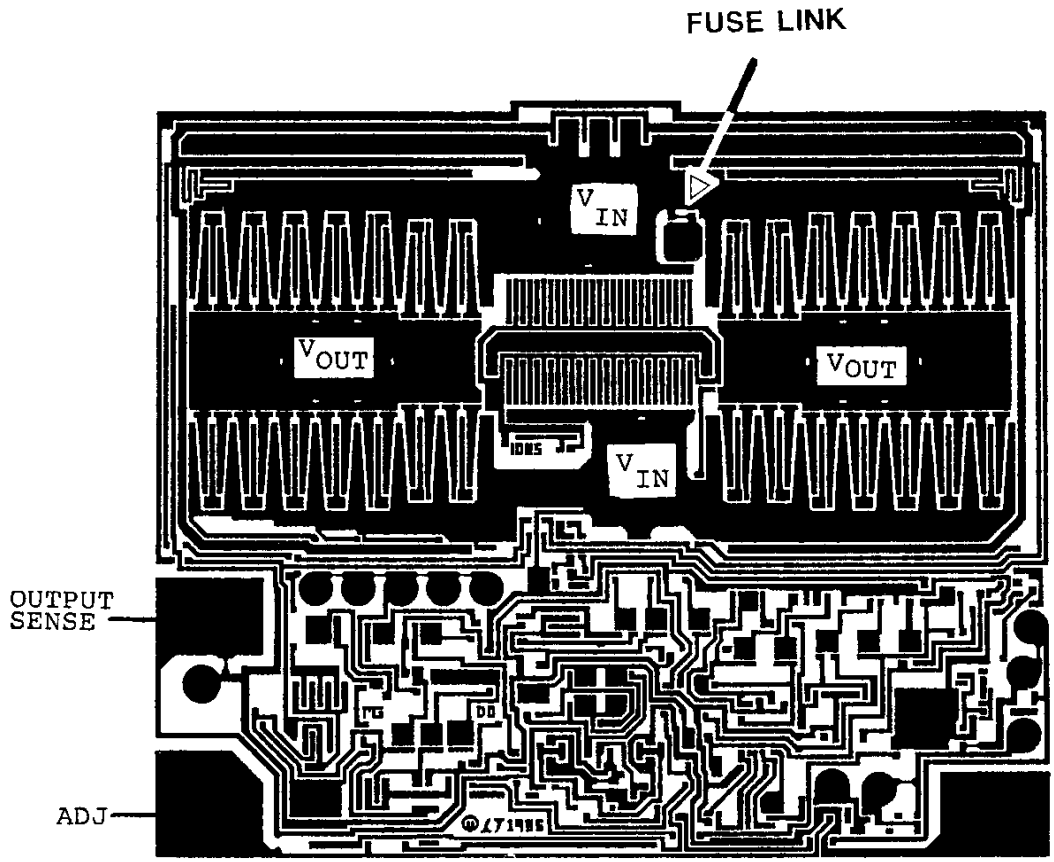


FIGURE 1A (Revision A)

DICE OUTLINE DIMENSIONS AND PAD FUNCTIONS

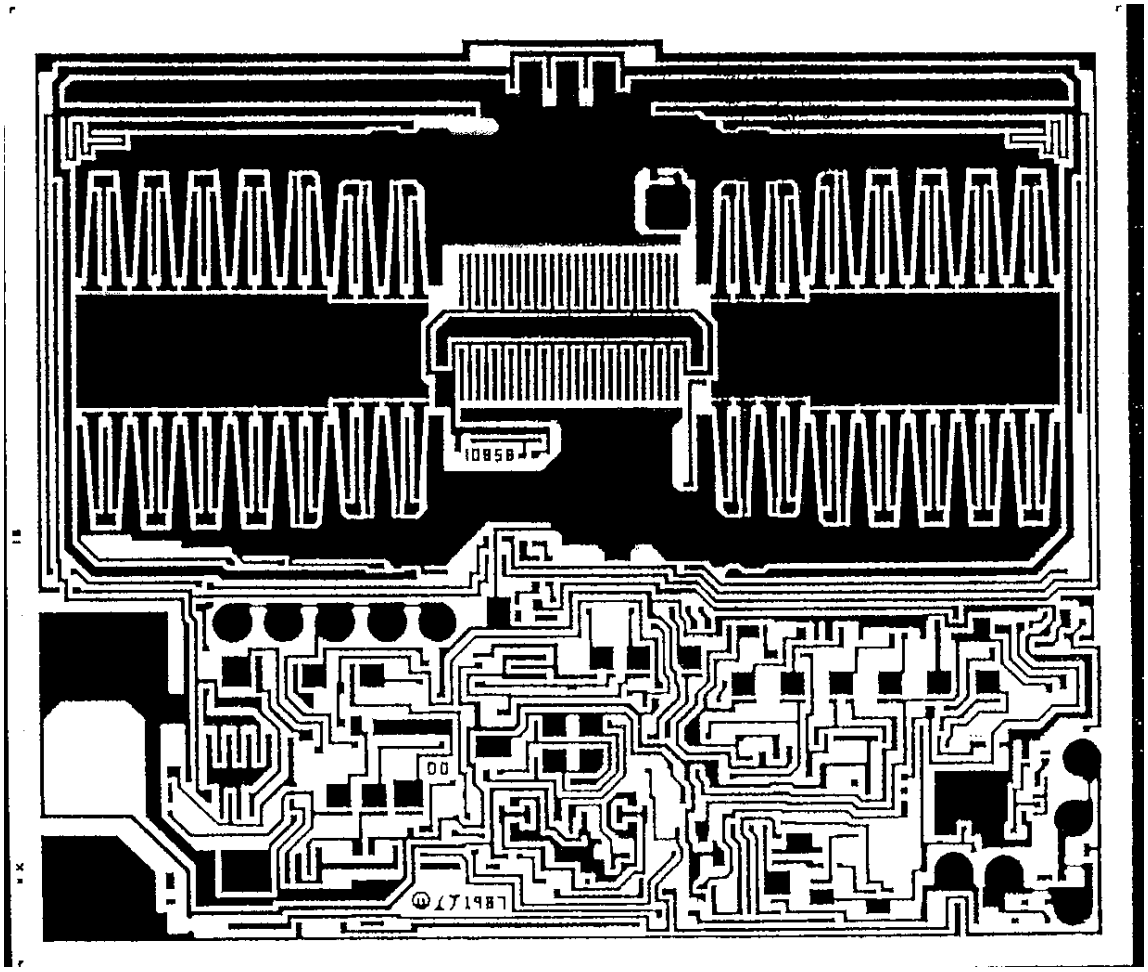


FIGURE 1B (Revision B)

TOTAL DOSE BIAS CIRCUIT

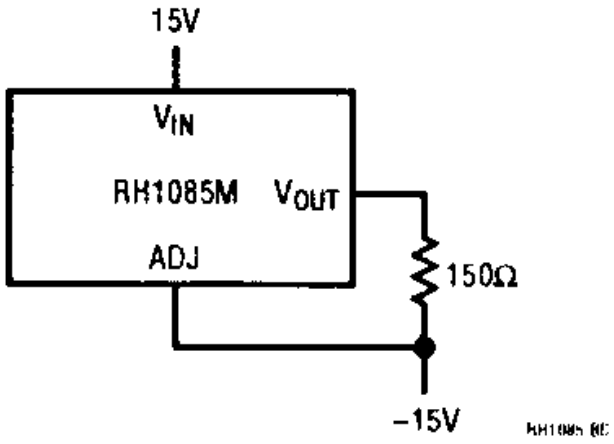
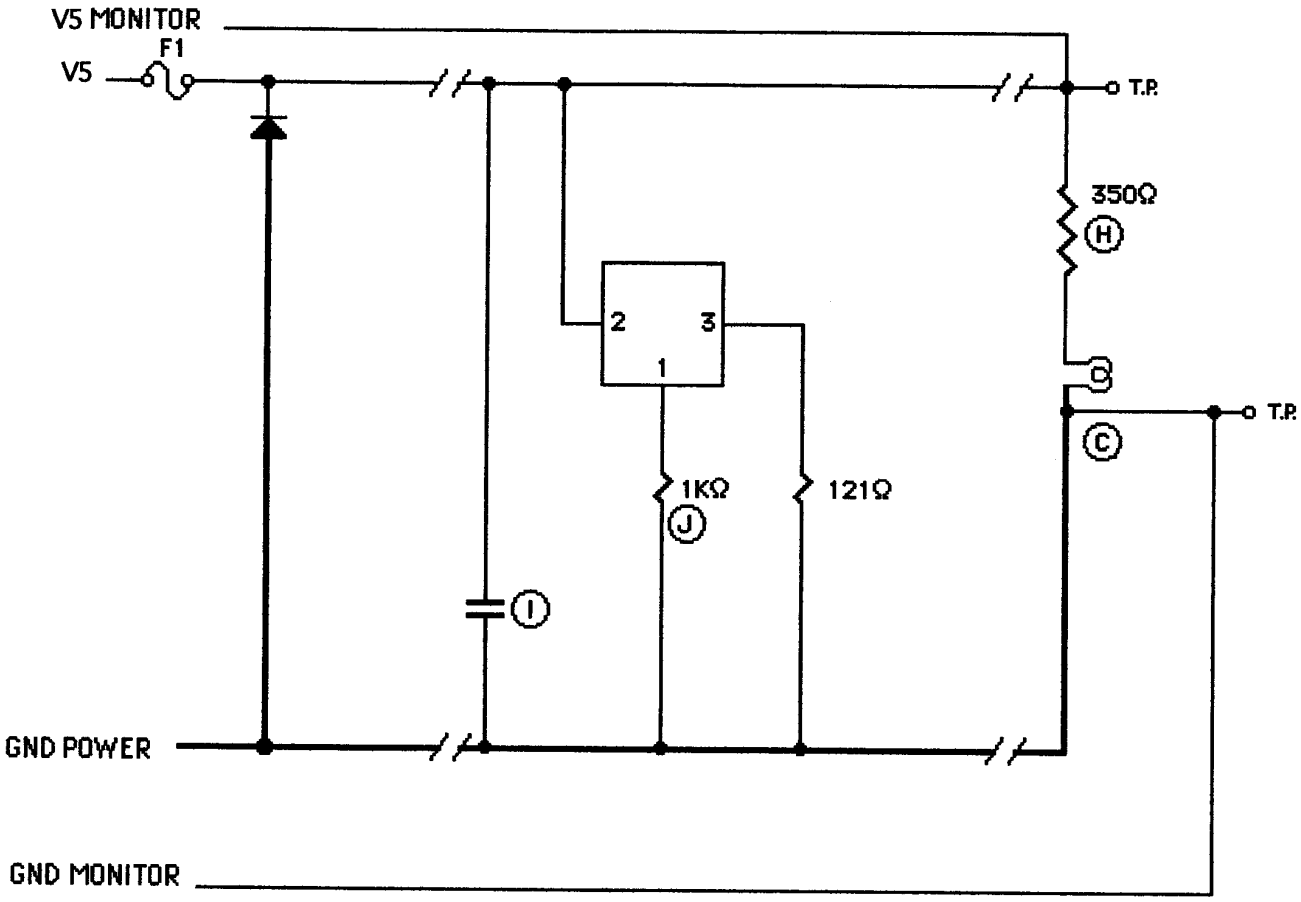


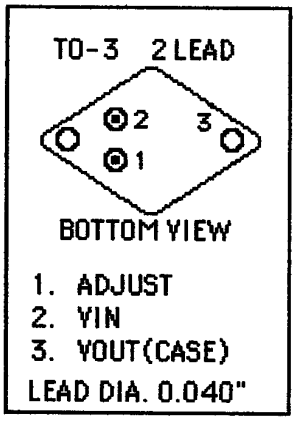
FIGURE 2

BURN-IN CIRCUIT



NOTES:

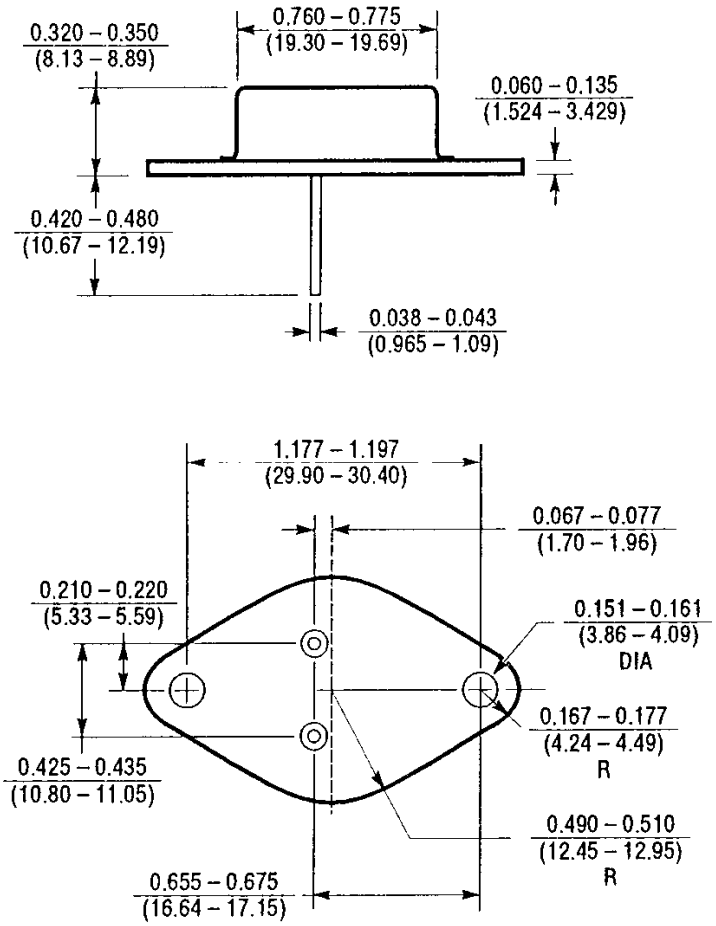
Unless otherwise specified, component tolerances shall be per military specification.
For RH1085
Burn-In Voltage to be V5 = +28V to +30V
Tj = 170 °C max at Ta of 150 °C.
Tj = 145 °C max at Ta of 125 °C.



PACKAGE AND PINOUT

FIGURE 3

TO3, 2 LEADS, CASE OUTLINE



θja = +35°C/W
θjc = +3°C/W

FIGURE 4

TERMINAL CONNECTIONS

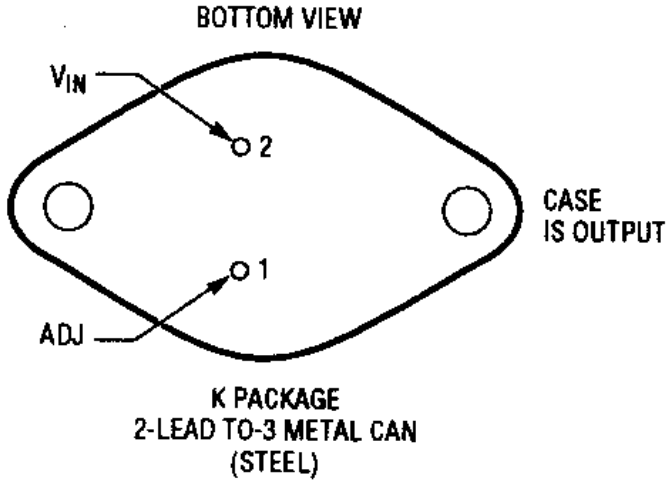


FIGURE 5

TABLE I DICE ELECTRICAL CHARACTERISTICS – Element Evaluation (Note 1)

PARAMETER	CONDITIONS	RH1085M (NOTE 6) MIN	MAX	UNITS
Reference Voltage	I_{OUT} = 10mA, T_J = 25°C, (V_{IN} - V_{OUT}) = 3V	1.238	1.262	V
	1.5V ≤ (V_{IN} - V_{OUT}) = 15V	1.225	1.270	V
Line Regulation	I_{LOAD} = 10mA, 1.5V ≤ (V_{IN} - V_{OUT}) ≤ 15V T_J = 25°C		0.2	%
Load Regulation	(V_{IN} - V_{OUT}) = 3V, 10mA ≤ I_{OUT} ≤ $I_{FULL\ LOAD}$ T_J = 25°C (NOTES 1,2,5)		0.3	%
Dropout Voltage (V_{IN} - V_{OUT})	ΔV_{OUT}, ΔV_{REF} = 1%, I_{OUT} = $I_{FULL\ LOAD}$ (NOTES 3, 5)		1.5	V
Current Limit	(V_{IN} - V_{OUT}) = 5V	3.2		A
	(V_{IN} - V_{OUT}) = 25V (NOTE 5)	0.2		A
Minimum Load Current	(V_{IN} - V_{OUT}) = 25V (NOTE 4)		10	mA
Ripple Rejection	f = 120 H_Z, C_{OUT} = 25μF Tantalum I_{OUT} = $I_{FULL\ LOAD}$ C_{ADJ} = 25μF, (V_{IN} - V_{OUT}) = 3V (Note 5)	60		dB
Adjust Pin Current	T_j = 25°C		120	μA
Adjust Pin Current Change	10mA ≤ I_{OUT} ≤ $I_{FULL\ LOAD}$ 1.5V ≤ (V_{IN} - V_{OUT}) ≤ 15V (Note 5)		5	μA

Note 1: See thermal regulation specifications for changes in output voltage due to heating effects. Load and line regulation are measured at a constant junction temperature by low duty cycle pulse testing.

Note 2: Line and load regulation are guaranteed up to the maximum power dissipation of 30W. Power dissipation is determined by the input/output differential and the output current. Guaranteed maximum power dissipation will not be available over the full input/output voltage range. See Short Circuit Current Curve in the LT®1085 Series standard data sheet for available output current.

Note 3: Dropout voltage is specified over the full output current range of the device. Test points and limits are shown on the Dropout Voltage Curve in the LT®1085 standard data sheet.

Note 4: Minimum load current is defined as the minimum output current required to maintain regulation. At 25V input/output differential the device is guaranteed to regulate if the output current is greater than 10mA.

Note 5: Guaranteed by design or correlation to other test parameters, but not tested at wafer sort.

Note 6: For Mil-Std-883 compliance, current density specification, $I_{FULL\ LOAD}$ is derated to 2.0A.

TABLE II ELECTRICAL CHARACTERISTICS – Post-Irradiation

PARAMETER	CONDITIONS	10KRAD (Si) MIN	10KRAD (Si) MAX	20KRAD (Si) MIN	20KRAD (Si) MAX	50KRAD (Si) MIN	50KRAD (Si) MAX	100KRAD (Si) MIN	100KRAD (Si) MAX	200KRAD (Si) MIN	200KRAD (Si) MAX	UNITS
Reference Voltage (Note 6)	I_{OUT} = 10mA ($V_{IN} - V_{OUT}$) = 3V	1.234	1.262	1.230	1.262	1.225	1.262	1.220	1.262	1.205	1.262	V
	10mA ≤ I_{OUT} ≤ $I_{FULL\ LOAD}$ 1.7V ≤ ($V_{IN} - V_{OUT}$) ≤ 15V	1.220	1.275	1.219	1.275	1.215	1.275	1.210	1.275	1.20	1.275	V
Line Regulation (Notes 2, 3)	I_{OUT} = 10mA 1.5V ≤ ($V_{IN} - V_{OUT}$) ≤ 15V		0.2		0.21		0.23		0.25		0.3	%
Load Regulation (Notes 2, 3, 6)	($V_{IN} - V_{OUT}$) = 3V 10mA ≤ I_{OUT} ≤ $I_{FULL\ LOAD}$		0.3		0.3		0.3		0.3		0.3	%
Dropout Voltage (Note 4)	ΔV_{REF} = 1%, I_{OUT} = 3A		1.5		1.5		1.55		1.6		1.65	V
Current Limit	($V_{IN} - V_{OUT}$) = 5V ($V_{IN} - V_{OUT}$) = 25V	3.2 0.2		3.17 0.20		3.15 0.20		3.10 0.20		3.0 0.2		A A
Minimum Load Current	($V_{IN} - V_{OUT}$) = 25V		10		10		10		10		10	mA
Adjust Pin Current			120		120		120		120		120	µA
Adjust Pin Current Change (Note 6)	10mA ≤ I_{OUT} ≤ $I_{FULL\ LOAD}$ 1.5V ≤ ($V_{IN} - V_{OUT}$) ≤ 15V		5		5		5		5		5	µA

Note 1: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

Note 2: See thermal regulation specifications for changes in output voltage due to heating effects. Line and load regulation are measured at a constant junction temperature by low duty cycle pulse testing.

Note 3: Line and load regulation are guaranteed up to the maximum power dissipation of 30W for RH1085. Power dissipation is determined by the input/output differential voltage and the output current. Guaranteed maximum power dissipation will not be available over the full input/output voltage range.

Note 4: Dropout voltage is specified over the full output current range of the device. Test points and limits are shown on the Dropout Voltage curve in the LT®1085 data sheet.

Note 5: Guaranteed by design, characterization, or correlation to other tested parameters.

Note 6: For compliance with 883 revision C current density specifications, the RH1085 is rated to 2A.

TABLE III RH ELEMENT EVALUATION TABLE QUALIFICATION OF DICE SALES

RH CANNED SAMPLE TABLE FOR QUALIFYING DICE SALES

SUBGROUP	CLASS K/S	CLASS V	CLASS H/B	OPERATION	MIL-STD-883 METHOD	MIL-STD-883 CONDITION	QUANTITY (ACCEPT NUMBER)
1	X	X		SEM	2018	N/A	REF. METHOD 2018 FOR S/S
2	X	X	X	ELEMENT ELECTRICAL (WAFER SORT @ 25°C)			100%
3	X	X	X	ELEMENT VISUAL (2nd OP)	2010	A	100%
4	X	X	X	INTERNAL VISUAL (3rd OP)	2010	A	ASSEMBLED PARTS ONLY
	X	X		DIE SHEAR MONITOR	2019		
	X	X		BOND PULL MONITOR	2011		
5	X	X		STABILIZATION BAKE	1008	C	ASSEMBLED PARTS ONLY
	X	X		TEMPERATURE CYCLE	1010	C	
	X	X		CONSTANT ACCELERATION	2001	E	
	X	X		FINE LEAK	1014	A	
	X	X		GROSS LEAK	1014	C	
6	X	X		FIRST ROOM ELECTRICAL - READ & RECORD (REPLACE ANY ASSEMBLY-RELATED REJECTS)			45(0)
	X	X		PRE BURN-IN ELECT. READ & RECORD @ +125°C or +150°C, -55°C			
	X	X		BURN-IN: +125°C/240 hrs. or +150°C/120 hrs.	1015	+ 125°c MINIMUM 240 HOURS	
	X	X		POST BURN-IN ELECT. READ & RECORD @ 25°C			
	X	X		POST BURN-IN ELECT. READ & RECORD @ +125°C or +150°C, -55°C			
		X		TOTAL IRRADIATION DOSE	1019	A	
	X	X		PRE OP-LIFE ELECTRICAL @ 25°C READ & RECORD			
	X	X		OPERATING LIFE: +125°C/1000 hrs. or +150°C/500 hrs.	1005	+ 125°c MINIMUM 1000 HOURS	
	X	X		POST OP-LIFE ELECT. (R & R @ 25°C, +125°C OR +150°C, -55°C			
7	X	X	X	WIRE BOND EVALUATION	2011		15(0) OR 25(1) - # of wires

NOTE: LTC is not qualified to process to MIL-PRF-38534. This is an LTC imposed element evaluation that follows MIL-STD-883 test methods and conditions. Please note the quantity and accept number from Sample Size Series of 5%, accept on 0, and note that the actual sample and accept number does not begin until Subgroup 6 OP-LIFE.

NOTE: Tests within Subgroup 5 may be performed in any sequence.

NOTE: LTC's radiation tolerance (RH) die has a topside glassivation thickness of 4KA minimum.

NOTE: Sample sizes on the travelers may be larger than that indicated in the above table; however, the larger sample size is to accommodate extra units for replacement devices in the event of equipment or operator error and for assembly related rejects in Subgroup 6, and for Wire Bond Evaluation, Surgroup 7. The larger sample size is at all times kept segregated and, if used for qualification, has all the required processing imposed.